Power TO-220 Film Resistors



TO-220 Style Thick Film

Heat Sink Device

Features:

- TO-220 style package
- Miniature size
- Maximum power : size ratio
- High stability
- · Optimum heat dissipation
- High temperature molding
- Noninductive
- Copper heat sink molded into TO 850 package

Variations:

Tolerance to 0.05%

Special TC Lead length

Mechanical:

Terminal strength: 5lb. pull test

Solderability: Meets requirements of MIL-STD-202 Solvent resistance: Meets requirements of MIL-STD-202

Material:

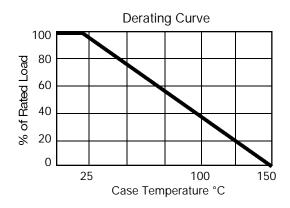
Heat sink: TO-850 Plated copper Element: High stability thick film

Leads: Tinned copper

Molding: High temperature thermoset

RGA Type TO 816-850

Temperature coefficient: Less than 10 ohms, 100ppm Above 10 ohms, 50ppm



TO-816 Power rating of 16 watts with heat sink. TO-850 Power rating of 50 watts with heat sink.

| | Series | Power Rating | Dielect. strength VAC | Max Voltage | Resistance (ohms) | |
|--|--------|-----------------|--------------------------|----------------|-------------------|-----|
| | | | | | Min | Max |
| | TO-816 | 16 Watts | 1500 | 300 | 0.1 | 20K |
| | TO-850 | 50 Watts | 1500 | 300 | 0.1 | 20K |

